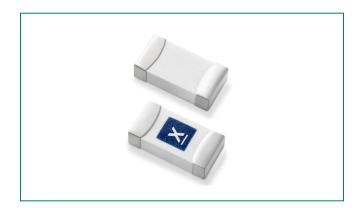


407A Series - 1206 Time-Lag Fuse





Agency Approvals

| AGENCY | AGENCY FILE NUMBER | AMPERE RANGE | | |
|-----------------|--------------------|--------------|--|--|
| c FL °us | E10480 | 1A – 8A | | |

Electrical Characteristics

| % of Ampere Rating | Ampere Rating | Opening Time at 25°C |
|-----------------------|------------------|------------------------------|
| 100% | 1A – 8A | 4 hours Minimum |
| 200% | 1A – 8A | 1 sec Min; 120 secs Max |
| 300% | 1A – 8A | 0.1 sec Min; 3 secs Max |
| 800% | 1A – 8A | 0.002 sec Min; 0.05 secs Max |

Description

The 407A Series AECQ-Compliant fuses are specifically tested to cater to secondary circuit protection needs of compact auto electronics applications.

The general design ensures excellent temperature stability and performance reliability. This high I2t fuse series is designed to have ultra high inrush current withstand capability to avoid nuisance fuse open.

Features

- Operating Temperature from -55° C to +150° C
- 100% Lead-free, RoHS compliant and Halogen-
- · Meets Littelfuse's automotive qualifications*
- Suitable for both leaded and lead-free reflow/wave soldering
- Ultra high l²t values

Benefits

- Avoids nuisance opening due to high inrush and surge current inherent in the system
- High current ratings in small size

Additional Information







Resources



Samples

Applications

- Li-ion Battery
- LED Lighting
- Automotive Navigation System
- TFT Display
- Battery Management System (BMS)
- Cluster

^{* -} Largely based on Littelfuse internal AEC-Q200 test plan.

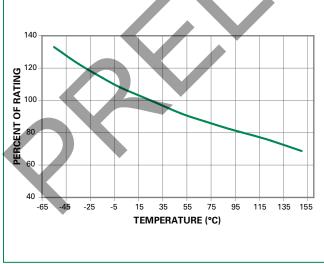


Electrical Specifications by Item

| Ampere Rating (A) | Amp Code | Max. Voltage Rating (V) | Interrupting Rating (AC/DC) ¹ | Nominal Resistance (Ohms) ² | Nominal Melting l²t (A²Sec.)³ | Nominal Voltage Drop At Rated Current (V)4 | Nominal Power Dissipation At Rated Current (W) | Agency Approval |
|-------------------------|-------------|----------------------------------|--|--|-------------------------------------|---|---|--------------------|
| 1.00 | 001. | 63 | | 0.360 | 0.142 | 0.456 | 0.456 | Х |
| 1.25 | 1.25 | 63 | 50A@63VDC | 0.200 | 0.329 | 0.404 | 0.500 | Х |
| 1.50 | 01.5 | 63 | 50A@63VDC | 0.180 | 0.567 | 0.347 | 0.525 | Х |
| 2.00 | 002. | 63 | | 0.100 | 0.870 | 0.323 | 0.640 | Х |
| 2.50 | 02.5 | 32 | | 0.055 | 1.000 | 0.252 | 0.625 | Х |
| 3.00 | 003. | 32 | | 0.040 | 1.300 | 0.187 | 0.570 | Х |
| 3.50 | 03.5 | 32 | 50A@32VDC | 0.030 | 2.260 | 0.153 | 0.525 | Х |
| 4.00 | 004. | 32 | 50A@32VDC | 0.025 | 4.180 | 0.142 | 0.560 | Х |
| 4.50 | 04.5 | 32 | | 0.020 | 5.200 | 0.134 | 0.585 | Х |
| 5.00 | 005. | 32 | | 0.016 | 7.800 | 0.133 | 0.650 | Х |
| 5.50 | 05.5 | 24 | 50A@24VDC | 0.014 | 8.550 | 0.130 | 0.715 | Х |
| 6.00 | 006. | 24 | 60A@24VDC | 0.012 | 15.560 | 0.128 | 0.780 | Х |
| 7.00 | 007. | 24 | | 0.010 | 16.230 | 0.110 | 0.770 | Х |
| 8.00 | 008. | 24 | | 0.009 | 24.120 | 0.097 | 0.800 | Х |

- 1. AC Interrupting Rating tested at rated voltage with unity power factor. DC Interrup Rating tested at rated voltage with time constant < 0.8 msec.
- 2. Nominal Resistance measured with < 10% rated current.
- 3. Nominal Melting I2t measured at 1msec. opening time.
- 4. Nominal Voltage Drop measured at rated current after temperature has stabilized
- Devices designed to carry rated current for 4 hours minimum. It is recommended that devices be operated continuously at no more than 80% rated current. See Temperature Derating Curve for additional derating information.
- Devices designed to be mounted with marking code facing up.

Temperature Re-rating Curve



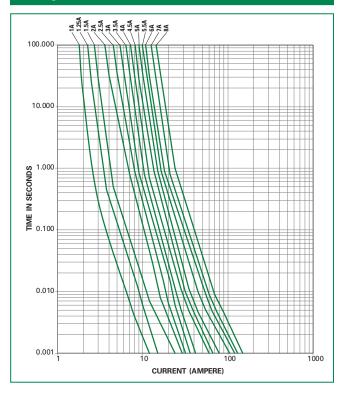
Re-rating depicted in this curve is in addition to the standard re-rating of 20% for continuous operation.

Example:

For continuous operation at 75° C, the fuse should be rerated as follows:

 $I = (0.80)(0.85)I_{RAT} = (0.68)I_{RAT}$

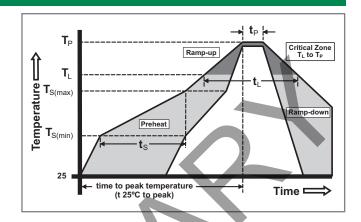
Average Time Current Curves





Soldering Parameters

| Reflow Co | ndition | Pb – free assembly | |
|--|--|--------------------|--|
| | -Temperature Min (T _{s(min)}) | 150°C | |
| Pre Heat | -Temperature Max (T _{s(max)}) | 200°C | |
| | -Time (Min to Max) (t _s) | 60 - 180 seconds | |
| Average R (T _L) to pea | amp-up Rate (Liquidus Temp k) | 3° C/second max. | |
| T _{S(max)} to T _I | - Ramp-up Rate | 5° C/second max. | |
| Reflow | -Temperature (T _L) (Liquidus) | 217° C | |
| | -Temperature (t _L) | 60 – 150 seconds | |
| PeakTemp | erature (T _P) | 260+0/-5 ° C | |
| Time with Temperatu | in 5°C of actual peak ure (t _p) | 10 - 30 seconds | |
| Ramp-dov | vn Rate | 6° C/second max. | |
| Time 25°C to peakTemperature (T _P) | | 8 minutes max. | |
| Do not exceed | | 260°C | |



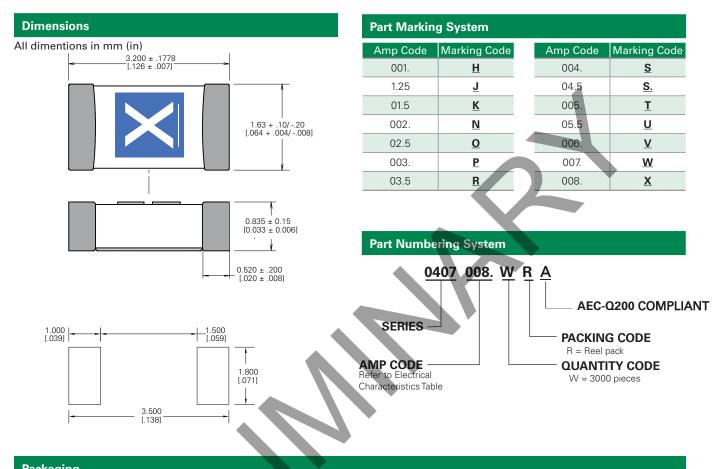
Wave soldering 260°C, 10 seconds max.

Product Characteristics

| Materials | Body: Advanced Ceramic Terminations: Ag / Ni / Sn (100% Lead-free) Element Cover Coating: Lead-free Glass | | |
|-------------------------------|---|--|--|
| Moisture Sensitivity Level | IPC/JEDEC J-STD-020, Level 1 | | |
| Solderability | IPC/ECA/JEDEC J-STD-002, Condition C | | |
| Humidity Test | MIL-STD-202, Method 103, Conditions D | | |
| Resistance to Solder Heat | MIL-STD-202, Method 210, Condition B | | |
| Moisture Resistance | MIL-STD-202, Method 106 | | |
| Thermal Shock | MIL-STD-202, Method 107, Condition B | | |
| Mechanical Shock | MIL-STD-202, Method 213, Condition A | | |
| Vibration | MIL-STD-202, Method 201 | | |
| Vibration, High Frequency | MIL-STD-202, Method 204, Condition D | | |
| Dissolution of Metallization | IPC/ECA/JEDEC J-STD-002, Condition D | | |
| Terminal Strength | IEC 60127-4 | | |

| High Temperature Storage | MIL-STD-202, Method 108 with exemptions | | |
|---------------------------------|---|--|--|
| Thermal Shock Test | JESD22 Method JA-104, Test Conditions B and N | | |
| Biased Humidity | MIL-STD-202, Method 103, 85C/85% RH with 10% operating power for 1000 hrs | | |
| Operational Life | MIL-STD-202, Method 108, Test Condition D | | |
| Resistance to Solvents | MIL-STD-202, Method 215 | | |
| Mechanical Shock | MIL-STD-202, Method 213, Test Condition C | | |
| High Frequency Vibration | MIL-STD-202, Method 204 | | |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Test Condition B | | |
| Solderability | JESD22-B102E Method 1 | | |
| Terminal Strength for SMD | AEC Q200-006 | | |
| Board Flex | AEC Q200-005 | | |
| Electrical Characterization | 3 Temperature Electrical | | |





| rackaging | | | | |
|-------------------|---------------|-------------------------------|----------|------------------------------|
| Packaging Option | Form Factor | Packaging Specification | Quantity | Quantity & Packaging Code |
| 8mm Tape and Reel | Surface Mount | EIA-481, IEC 60286, Part 3 | 3000 | WR |

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